



IEEE/SICE SII 2024

International Symposium on System Integration
HA LONG, VIETNAM 8-11th January, 2024



IEEE



Ha Long Bay

IEEE/SICE International Symposium on System Integration (SII) is the symposium series presenting the state of the art and future perspectives of system integration, where industrial experts, researchers, and academics share ideas and experiences surrounding frontier technologies, breakthrough and innovative solutions, and applications.

The IEEE/SICE SII 2024 will be the 16th symposium on system integration. System integration is one of the key technologies and the integration of hardware and software is especially important to solve the industrial or social system problems in the new century. This symposium focuses towards new research and industrial applications of system integration, and discusses approaches and methodologies to improve effectiveness of system integration.

Important Dates:

Proposals for Special Sessions

Jun. 30, 2023

Paper Submission

Aug. 1, 2023

Workshop Proposal Submission Deadline

Aug. 15, 2023

Notification of Workshop Proposal Acceptance

Sep. 15, 2023

Notification of Paper Acceptance

Oct. 1, 2023

Final Paper Submission

Oct. 15, 2023

Late Breaking Results Submission

Oct. 15, 2023

Notification of Late Breaking Results Acceptance

Oct. 29, 2023



FOLLOW US !



@SII_SICE

Contact: sii2024@ml.jaist.ac.jp

※ The date time are based on Pacific Time.

※ All proceedings will be published on IEEE Xplore, and indexed by Web of Science and Scopus.

Host University



General Chair
Van Anh Ho, Japan Advanced Institute of Science and Technology, Japan.

General Co-chair
Gordon Cheng, The Technical University of Munich, Germany.
Jun Ueda, Georgia Institute of Technology, United States.

Program Chair
Trung Dung Ngo, University of Prince Edward Island, Canada.

Program Co-Chairs
Hung (Jim) La, University of Nevada, United States.
Mochiyama Hiromi, University of Tsukuba, Japan.
Matteo Bianchi, University of Pisa, Italy.

Special Sessions Chairs
Mihoko Niitsuma, Chuo University, Japan.

Yonghoon Ji, Japan Advanced Institute of Science and Technology, Japan.

Workshop Chair
Zhongkui Wang, Ritsumeikan Univ, Japan

Publication Chairs
Thanh Nho Do, The University of New South Wales, Australia.
Yongsheng Ou, Chinese Academy of Sciences.

Industry Chair
Son Tong, Siemens, Belgium.

Publicity Chair
Amy Kyungwon Han, Seoul National University, Korea.

Local Arrangement
Thanh Tung Bui, VNU University of Engineering and Technology, Vietnam.

Financial Chairs

Pham Hung, VNU University of Engineering and Technology, Vietnam.
Dinh Quang Nguyen, Hanoi University of Industry, Vietnam.

Regional Chairs
Kumeresan A. D., University of Technology Malaysia, Malaysia.
Wee Hong Ong, Universiti Brunei Darussalam, Brunei.
John-Josef Leth, Aalborg University, Denmark.
Muhammad Iqbal, Tampere University, Finland.
Pakpong CHIRARATTANANON, City University of Hong Kong, China
Lum Guo Zhan, Nanyang Technological University, Singapore
Zhu Jian, Chinese University of Hong Kong, China

Administrative Support Members
Nhan Huu Nguyen, Japan Advanced Institute of Science and Technology, Japan.
Dinh Minh Nhat Le, Japan Advanced Institute of Science and Technology, Japan.

Photo credit: Thanh Chung